

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJK2009
Package Type :	SOT-23-3L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	3.69%
Lead Frame	Copper	7440-50-8	97.47%	37.52%
	Iron	7439-89-6	2.30%	
	Phosphorus	7723-14-0	0.05%	
	Zinc	7440-66-6	0.10%	
	Lead	7439-92-1	0.03%	
	Silver	7440-22-4	0.05%	
Epoxy	Silver	7440-22-4	76.00%	0.24%
	bisphenol-F-(epichlorhydrin)	Proprietary	15.00%	
	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8	7.00%	
	dapsone	80-08-0	2.00%	
Wire	Copper	7440-50-8	99.99%	1.36%
	Others	/	0.01%	
Mold Compound	Solid Epoxy Resin	Trade Secret	9.00%	55.58%
	Hardener	Trade Secret	5.50%	
	Amorphous silica	60676-86-0	83.00%	
	Carbon Black	1333-86-4	0.50%	
	Metal Hydroxide	Trade Secret	2.00%	
Plating	Tin	7440-31-5	99.90%	1.60%
	Other	/	0.10%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.